

AMENDMENTS TO THE SPECIFICATION:

Please amend the paragraph on page 2, lines 5 to 9, as follows:

~~With~~ Lateral chip dimensions of approximately 1 mm, ~~it has been~~ are quite some  
~~time since~~ below dimensions where conventional housings ("tub" with lid) could be used.  
For these reasons, ~~all the~~ leading semiconductor manufacturers have developed packaging  
concepts[[,]] in recent years, which provide for ~~the~~ encapsulation ~~process completely~~ on  
the wafer level, i.e., before individualization of the components, after wafer structuring.

Please amend the paragraph on page 7, lines 6 to 14, as follows:

In an advantageous embodiment of the invention, the frame structure surrounds the  
components structures in ring shape, ~~for one thing,~~ and, furthermore, forms branches  
~~runners~~ or insulated islands that face inward, ~~which.~~ These surround another cavity within  
the sandwich-like structure, in which the connector metallizations ~~lie~~ are exposed on the  
surface of the chip. In this manner, it is possible to guide the interfacial connections  
through the cover, into these additional cavities, without the cavity with the component  
structures being opened. This also makes it possible to keep the component structures free  
of metallization during the production of the underside metallization, without additional  
efforts being required for this purpose, for seals or covers.

Please amend the paragraph on page 13, lines 1 to 8, as follows:

Figure 2 shows the arrangement of the frame structure RS, in a schematic top view  
of the front face of the chip CH. The structure is closed in a ring shape in the outside

region of the chip surface. In the embodiment shown here, the frame structure has a ~~branch runner~~ AL, which is also closed in ring shape, which surrounds another, smaller region within the frame structure. This is the region also shown in Figure 1, in which the interfacial connection is provided, so that there, the underside metallization ~~Um~~ UM can enter into contact with the connector metallization~~[[,]]~~. The connector metallization ~~which in turn~~ is connected with the component structures BS in electrically conductive manner.

Please amend the paragraph on page 15, lines 13 to 15, as follows:

Not shown in Figure 5 are ~~runners~~ branches of the frame structure or islands, ~~which~~. The branches surround the regions of the surface of the wafer in a ring shape, as shown in Figure 2 for ~~the~~ an individual component, in which ~~the~~ contacts to the contact metallization AM are provided.

Please amend the paragraph on page 21, lines 6 to 10, as follows:

Before or after production of the cuts, it is possible to reduce the thickness of the wafer from the back. In this ~~connection~~ arrangement, it can be ground down to a layer thickness of approximately 50  $\mu\text{m}$ , or ~~worn away~~ ablated in some other way. The firm connection with the frame structure and the cover assures sufficient mechanical stability in spite of the low layer thickness~~[[,]]~~ so that the components are not damaged and their ~~function~~ operability is not impaired.

Please amend the paragraph on page 22, lines 15 to 18, as follows:

- The working depth can be controlled very accurately using an excimer laser, by means of the number and the energy of the laser pulses. Since different materials have different ~~wear~~ ablation threshold intensities, an automatic shutdown of the processing when a border surface has been reached can also be achieved.